Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSV)

2SK2544

Switching Regulator Applications

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & :\ RDS\ (ON) = 0.9\ \Omega(typ.) \\ \bullet & High\ forward\ transfer\ admittance & :\ |\ Y_{fs}| = 5.5\ S\ (typ.) \\ \bullet & Low\ leakage\ current & :\ IDSS = 100\ \mu A\ (max)\ (VDS = 600\ V) \\ \bullet & Enhancement\ mode & :\ V_{th} = 2.0 {\sim} 4.0\ V\ (VDS = 10\ V,\ ID = 1\ mA) \end{array}$

Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	600	V	
Drain-gate voltage (R	_{GS} = 20 kΩ)	V _{DGR}	600	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	6	Α	
	Pulse (Note 1)	I _{DP}	24	А	
Drain power dissipation	n (Tc = 25°C)	P_{D}	80	W	
Single pulse avalanche energy (Note 2)		E _{AS}	345	mJ	
Avalanche current		I _{AR}	6	А	
Repetitive avalanche energy (Note 3)		E _{AR}	8	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature ra	ange	T _{stg}	-55~150	°C	

10.3MAX. 03.6±0.2 10.3MAX. 0.76 10.3MAX. 0.76 10.3MAX. 0.76 10.3MAX. 0.76 11.6MAX. 0.76 11.6MAX. 0.76 12.54

TO-220AB

SC-46

2-10P1B

Weight: 2.0 g (typ.)

JEDEC

JEITA

TOSHIBA

2. DRAIN (HEAT SINK)
3. SOURCE

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.56	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	83.3	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C...

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 16.8 mH, R_G = 25 Ω , I_{AR} = 6 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



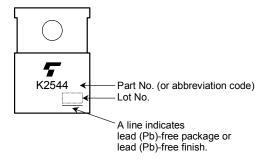
Electrical Characteristics (Ta = 25°C)

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V _{GS} = ±25 V, V _{DS} = 0 V	_	_	±10	μΑ
Gate-source bro	eakdown voltage	V (BR) GSS	$I_{G} = \pm 10 \ \mu A, \ V_{GS} = 0 \ V$	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 600 V, V _{DS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	600	_	_	V
Gate threshold v	/oltage	V_{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	٧
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 3 A	_	0.9	1.25	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3 A	2.0	5.5	_	S
Input capacitano	ce	C _{iss}		_	1300	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	130	_	pF
Output capacitance		Coss		_	400	_	
Switching time	Rise time	t _r	V_{GS} V_{OV} V_{OU} V_{OU} V_{OU} V_{OU} V_{OU} V_{OU} V_{OU} V_{OU}	_	25	_	ns
	Turn-on time	t _{on}		_	45	_	
	Fall time	t _f		_	40	_	
	Turn-off time	t _{off}	Duty $\leq 1\%$, $t_{\rm W} = 10 \mu \rm s$	_ 150 _			
Total gate charge (Gate-source plus gate-drain)		Qg			30		
Gate-source charge		Q _{gs}	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 6 \text{ A}$		18	_	nC
Gate-drain ("miller") charge		Q _{gd}			12	_	

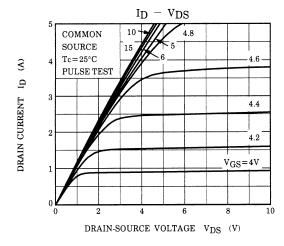
Source-Drain Ratings and Characteristics (Ta = 25°C)

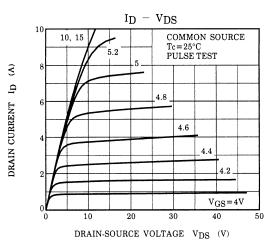
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	_	_	_	6	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	24	Α
Forward voltage (diode)	V_{DSF}	I _{DR} = 6 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 6 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs	1	1000		ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 100 A / μs	- 1	7	_	μC

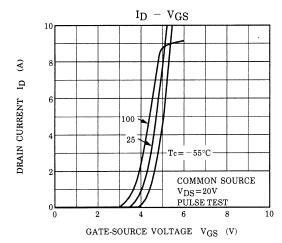
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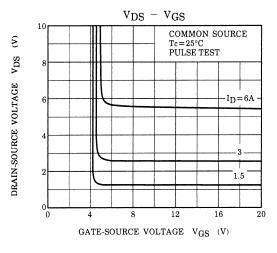


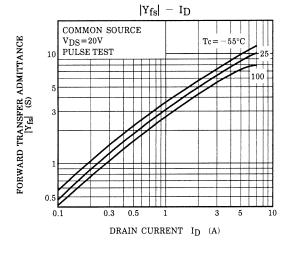
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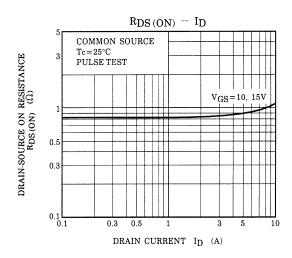


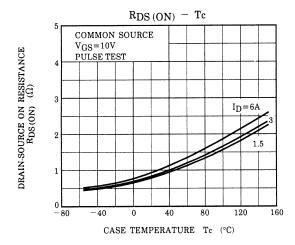


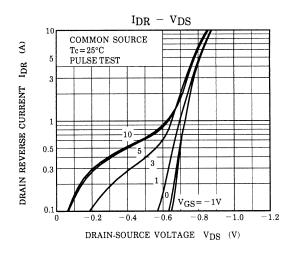


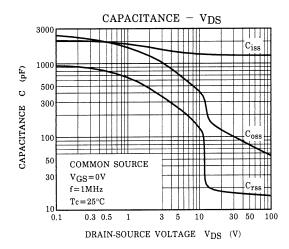


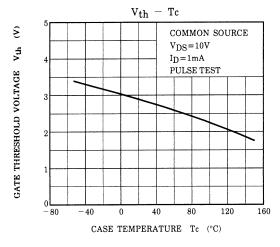


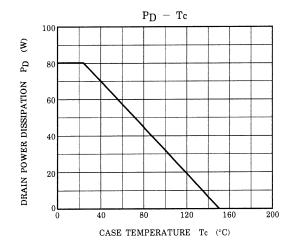


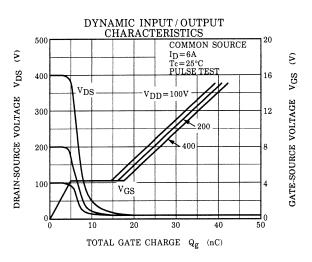


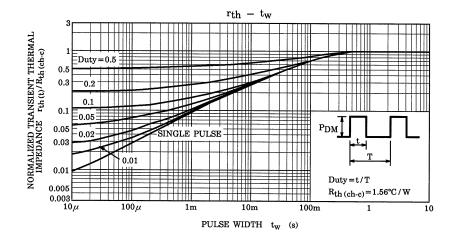


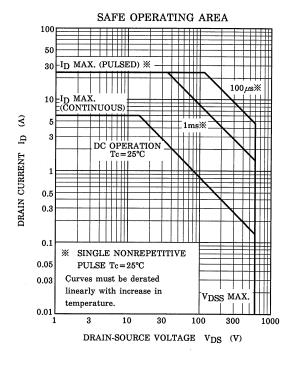


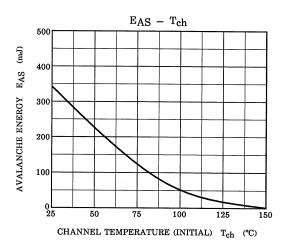


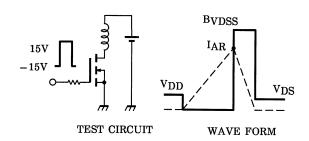












$$R_G = 25 \Omega$$

 $V_{DD} = 90 \text{ V}, L = 16.8 \text{ mH}$

$$EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right)$$

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Handbook" etc..

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